

**BCV72**  
**SURFACE MOUNT SILICON**  
**NPN TRANSISTOR**



**SOT-23 CASE**

**DESCRIPTION:**

The CENTRAL SEMICONDUCTOR BCV72 is a silicon NPN transistor manufactured by the epitaxial planar process, epoxy molded in a surface mount package, designed for general purpose applications.

**MARKING CODE: K8**

**MAXIMUM RATINGS:** ( $T_A=25^\circ\text{C}$ )

Collector-Base Voltage
Collector-Emitter Voltage
Emitter-Base Voltage
Continuous Collector Current
Peak Collector Current
Power Dissipation
Operating and Storage Junction Temperature
Thermal Resistance

SYMBOL		UNITS
$V_{CBO}$	80	V
$V_{CEO}$	60	V
$V_{EBO}$	5.0	V
$I_C$	100	mA
$I_{CM}$	200	mA
$P_D$	350	mW
$T_J, T_{stg}$	-65 to +150	$^\circ\text{C}$
$\theta_{JA}$	357	$^\circ\text{C/W}$

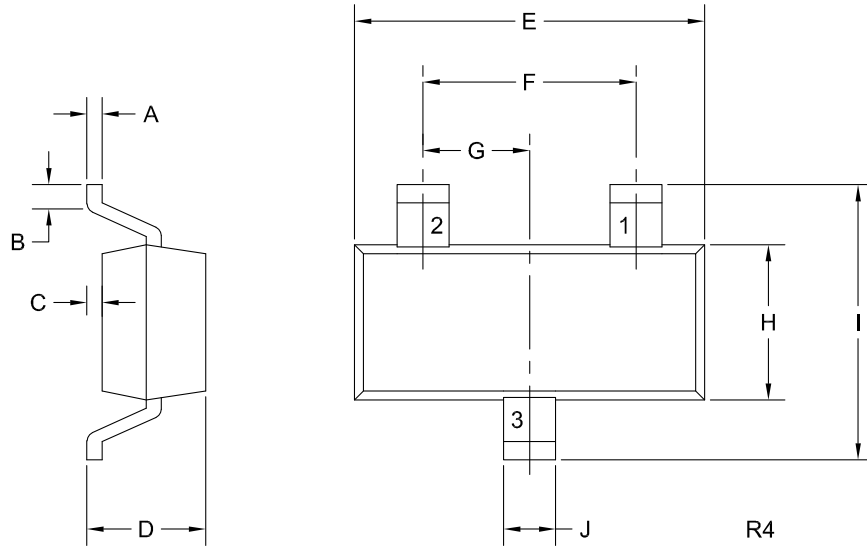
**ELECTRICAL CHARACTERISTICS:** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
$I_{CBO}$	$V_{CB}=20\text{V}$			100	nA
$I_{CBO}$	$V_{CB}=20\text{V}, T_A=100^\circ\text{C}$			10	$\mu\text{A}$
$BV_{CEO}$	$I_C=2.0\text{mA}$	60			V
$BV_{CBO}$	$I_C=10\mu\text{A}$	80			V
$BV_{EBO}$	$I_C=10\mu\text{A}$	5.0			V
$V_{CE(SAT)}$	$I_C=10\text{mA}, I_B=0.5\text{mA}$			250	mV
$V_{BE(ON)}$	$V_{CE}=5.0\text{V}, I_C=2.0\text{mA}$	550		700	mV
$h_{FE}$	$V_{CE}=5.0\text{V}, I_C=2.0\text{mA}$	200		450	
$C_{ob}$	$V_{CB}=10\text{V}, I_E=0, f=1.0\text{MHz}$		2.5		pF
$f_T$	$V_{CE}=5.0\text{V}, I_C=10\text{mA}, f=35\text{MHz}$		300		MHz
NF	$V_{CE}=5.0\text{V}, I_C=200\mu\text{A}, R_S=2.0\text{k}\Omega$ $f=1.0\text{kHz}, B=200\text{Hz}$			10	dB

**BCV72**  
**SURFACE MOUNT SILICON**  
**NPN TRANSISTOR**



**SOT-23 CASE - MECHANICAL OUTLINE**



**LEAD CODE:**

- 1) Base
- 2) Emitter
- 3) Collector

**MARKING CODE: K8**

<b>DIMENSIONS</b>				
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.003	0.007	0.08	0.18
B	0.006	-	0.15	-
C	-	0.005	-	0.13
D	0.035	0.044	0.89	1.12
E	0.110	0.120	2.80	3.05
F	0.075		1.90	
G	0.037		0.95	
H	0.047	0.055	1.19	1.40
I	0.083	0.104	2.10	2.64
J	0.014	0.020	0.35	0.50

SOT-23 (REV: R4)

R2 (21-October 2021)

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



---

### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

---

### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

---

### REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

---

### CONTACT US

#### Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.  
145 Adams Avenue  
Hauppauge, NY 11788 USA  
Main Tel: (631) 435-1110  
Main Fax: (631) 435-1824  
Support Team Fax: (631) 435-3388  
[www.centrasemi.com](http://www.centrasemi.com)

**Worldwide Field Representatives:**  
[www.centrasemi.com/wwreps](http://www.centrasemi.com/wwreps)

**Worldwide Distributors:**  
[www.centrasemi.com/wwdistributors](http://www.centrasemi.com/wwdistributors)

---

For the latest version of Central Semiconductor's **LIMITATIONS AND DAMAGES DISCLAIMER**, which is part of Central's Standard Terms and Conditions of sale, visit: [www.centrasemi.com/terms](http://www.centrasemi.com/terms)